

PART INFORMATION		
Mfg Item Number		MCIMX6L2DVN10AB
Mfg Item Name		MAPBGA 432 13*13 P0.5
SUPPLIER		
Company Name		Freescale Semiconductor Inc
Company Unique ID		14-141-7928
Response Date		2018-04-25
Response Document ID		00CHA1.8
Contact Name		Freescale Semiconductor Inc
Contact Title		Product Technical Support
Contact Phone		1-800-521-6274
Contact Email		support@freescale.com
Authorized Representative		Daniel Binyon
Representative Title		EPP Customer Response
Representative Phone		512-895-3406
Representative Email		eppanlst@freescale.com
URL for Additional Information		www.freescale.com
DECLARATION		
EU RoHS		Yes
Pb Free		Yes
HalogenFree		Yes
Plating Indicator		e1
EU RoHS Exemption(s)		
MANUFACTURING		
Mfg Item Number		MCIMX6L2DVN10AB
Mfg Item Name		MAPBGA 432 13*13 P0.5
Version		ALL
Weight		0.587900
UoM		g
Unit Volume		EACH
J-STD-020 MSL Rating		3
Peak Processing Temperature		260 C
Max Time at Peak Temperature		40 seconds
Number of Processing Cycles		3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0015						g					
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0001125	g	75000	7.5		191	0.0191
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.0003	g	200000	20		510	0.051
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.0001125	g	75000	7.5		191	0.0191
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.0003	g	200000	20		510	0.051
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.000675	g	450000	45		1148	0.1148
Bonding Wire, PdCu	0.0037						g					
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.00362968	g	980994	98.0994		6173	0.6173
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.0000037	g	1000	0.1		6	0.0006
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.00006662	g	18006	1.8006		113	0.0113
Solder Balls - Lead Free	0.2203						g					
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.0011026	g	5005	0.5005		1875	0.1875
Solder Balls - Lead Free		Nickel (external applications only)	Nickel	7440-02-0		0.00011037	g	501	0.0501		187	0.0187
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.00264646	g	12013	1.2013		4501	0.4501
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.21644057	g	982481	98.2481		368172	36.8172
Die Encapsulant, Halogen-free	0.2362						g					
Die Encapsulant, Halogen-free		Metals	Aluminum, metal	7429-90-5		0.005905	g	25000	2.5		10044	1.0044
Die Encapsulant, Halogen-free		Metals	Magnesium, metal	7439-95-4		0.002362	g	10000	1		4017	0.4017
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.002362	g	10000	1		4017	0.4017
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Silicone modified epoxy resin	218163-11-2		0.027163	g	115000	11.5		46203	4.6203
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.002362	g	10000	1		4017	0.4017
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.18896	g	800000	80		321415	32.1415
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other acrylic/epoxy resin mixture	-		0.001181	g	5000	0.5		2008	0.2008
Die Encapsulant, Halogen-free		Glass	Silica, amorphous synthetic	112926-00-8		0.005905	g	25000	2.5		10044	1.0044
Organic Substrate, Halogen-fre	0.112						g					
Organic Substrate, Halogen-fre		Metals	Barium sulfate	7727-43-7		0.0073957	g	66033	6.6033		12579	1.2579
Organic Substrate, Halogen-fre		Metals	Copper, metal	7440-50-8		0.05602822	g	500252	50.0252		95302	9.5302
Organic Substrate, Halogen-fre		Metals	Gold, metal	7440-57-5		0.00347368	g	31015	3.1015		5908	0.5908
Organic Substrate, Halogen-fre		Metals	Talc	14807-96-6		0.00005555	g	496	0.0496		94	0.0094
Organic Substrate, Halogen-fre		Nickel (external applications only)	Nickel	7440-02-0		0.02521277	g	225114	22.5114		42886	4.2886
Organic Substrate, Halogen-fre		Solvents, additives, and other materials	Silicone modified epoxy resin	218163-11-2		0.0056028	g	50025	5.0025		9530	0.953
Organic Substrate, Halogen-fre		Glass	Fibrous-glass-wool	65997-17-3		0.0057148	g	51025	5.1025		9720	0.972
Organic Substrate, Halogen-fre		Glass	Silica, vitreous	60676-86-0		0.00851648	g	76040	7.604		14486	1.4486
Silicon Semiconductor Die	0.0142						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000284	g	20000	2		483	0.0483
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.013916	g	980000	98		23670	2.367

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MCIMX6L2DVN10AB_IPC1752_v11.xml

http://www.freescale.com/mcds/MCIMX6L2DVN10AB_IPC1752A.xml